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(12) **United States Design Patent**
Feng

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(54) **LIGHT EMITTING DIODE CHIP**

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- (51) **LOC (10) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/180**

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D25/155, 160, 163; D26/1
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/0079; H01L 33/04; H01L 33/08;
H01L 33/10; H01L 33/20; H01L 33/38;
H01L 33/42; H01L 33/4448; H01L 33/483;
H01L 33/486; H01L 24/06; H01J 3/021;
H01S 5/34; F21K 9/00; F21K 9/30; F21K
9/54; B82Y 20/00; B82Y 40/00
See application file for complete search history.

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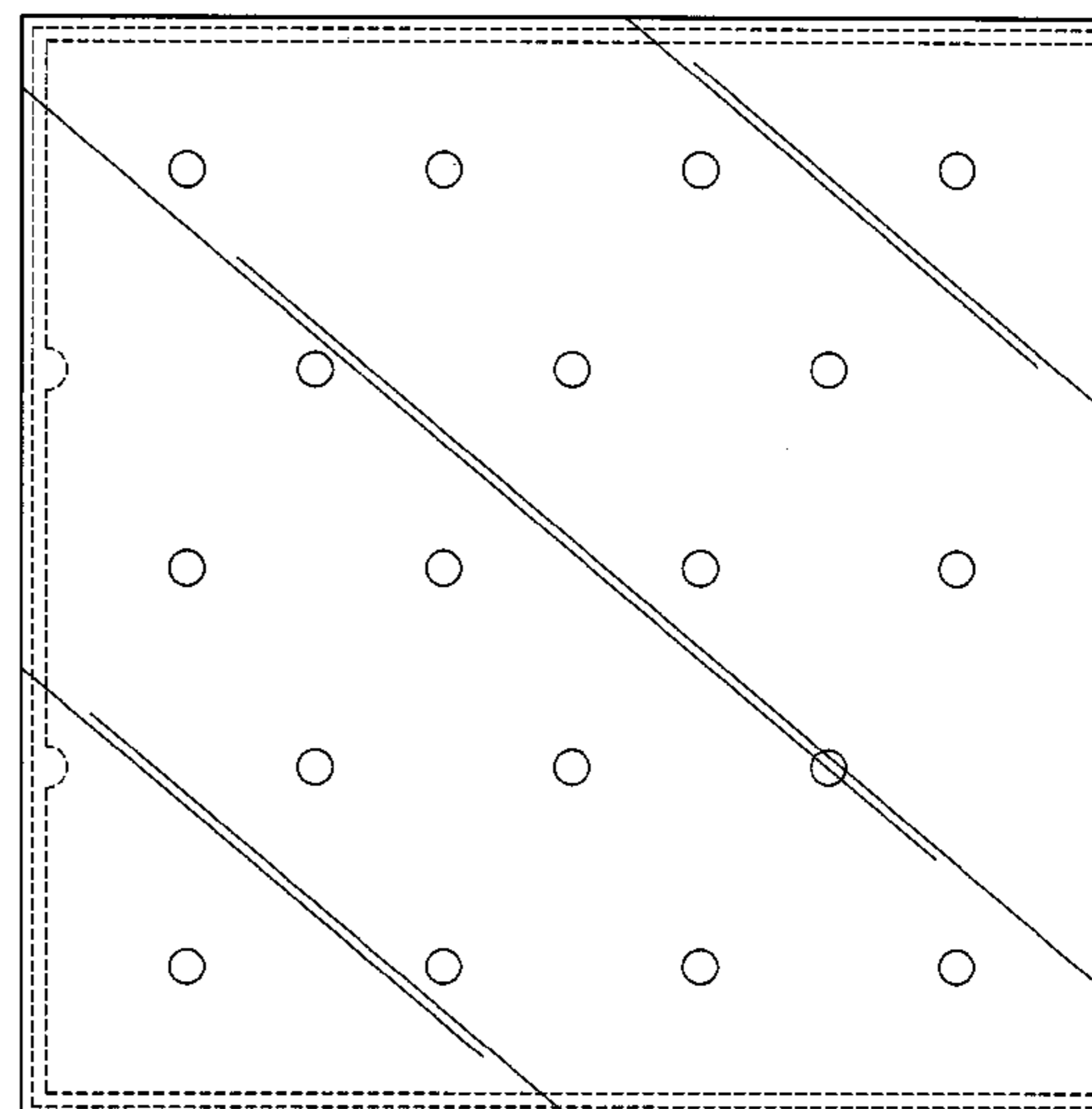
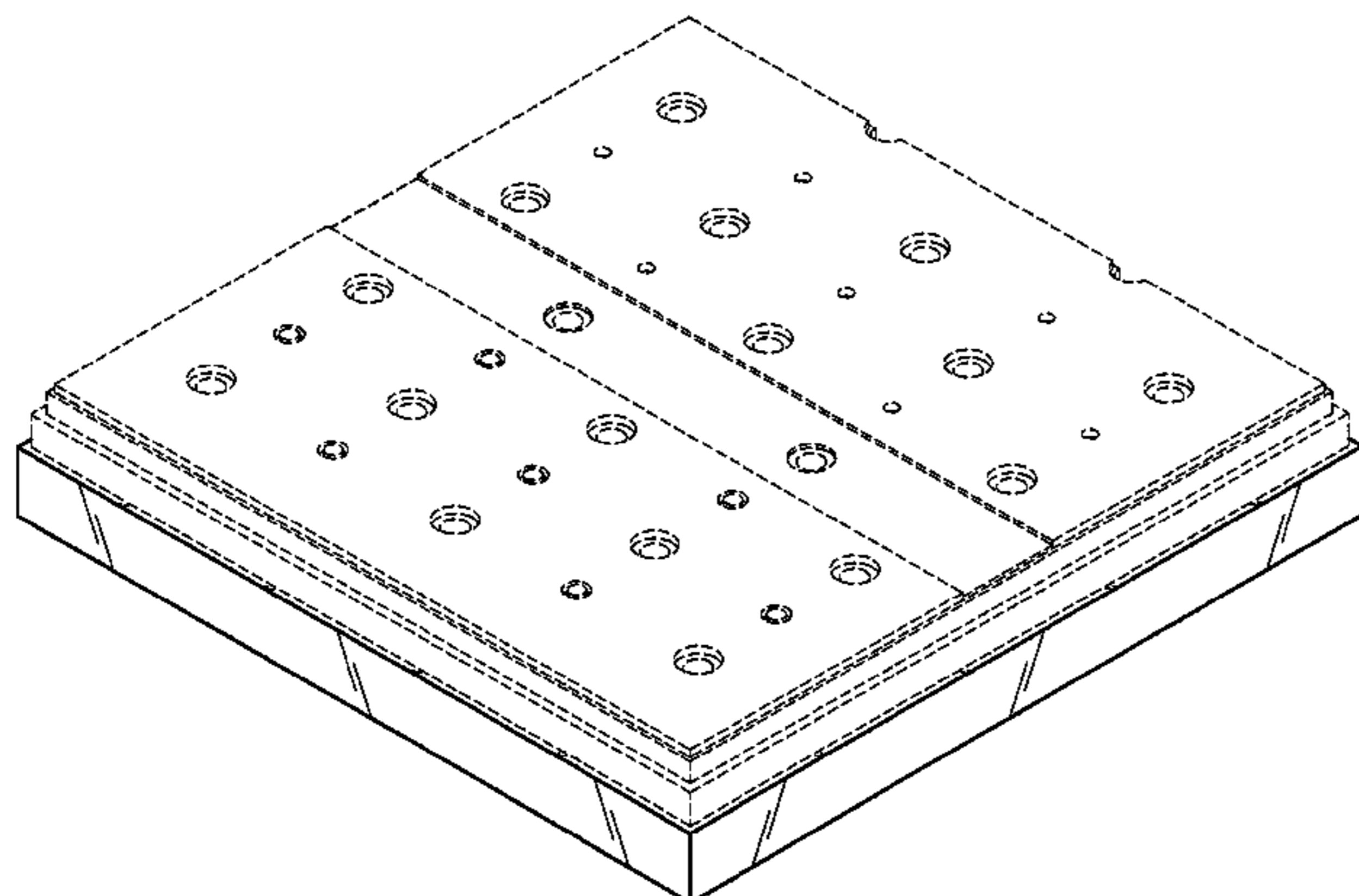
(57) **CLAIM**

The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode chip showing an embodiment of my new design;
 FIG. 2 is a front view of the embodiment;
 FIG. 3 is a rear view of the embodiment;
 FIG. 4 is a left side view of the embodiment;
 FIG. 5 is a right side view of the embodiment;
 FIG. 6 is a top view of the embodiment; and,
 FIG. 7 is a bottom view of the embodiment.
 The broken line portions of the light emitting diode chip in FIGS. 1-7 represent unclaimed portions of the design and form no part thereof.

1 Claim, 5 Drawing Sheets



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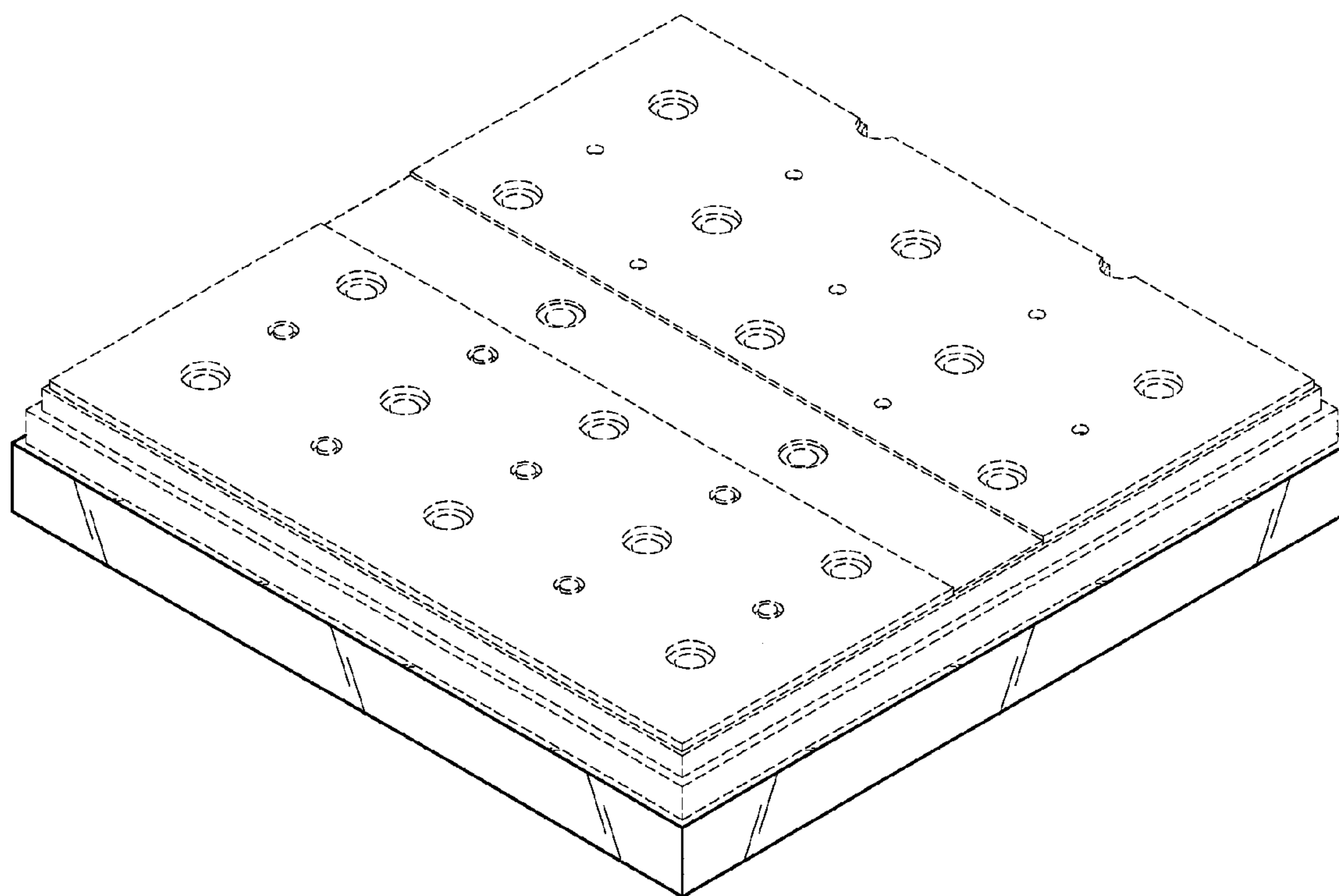


FIG. 1

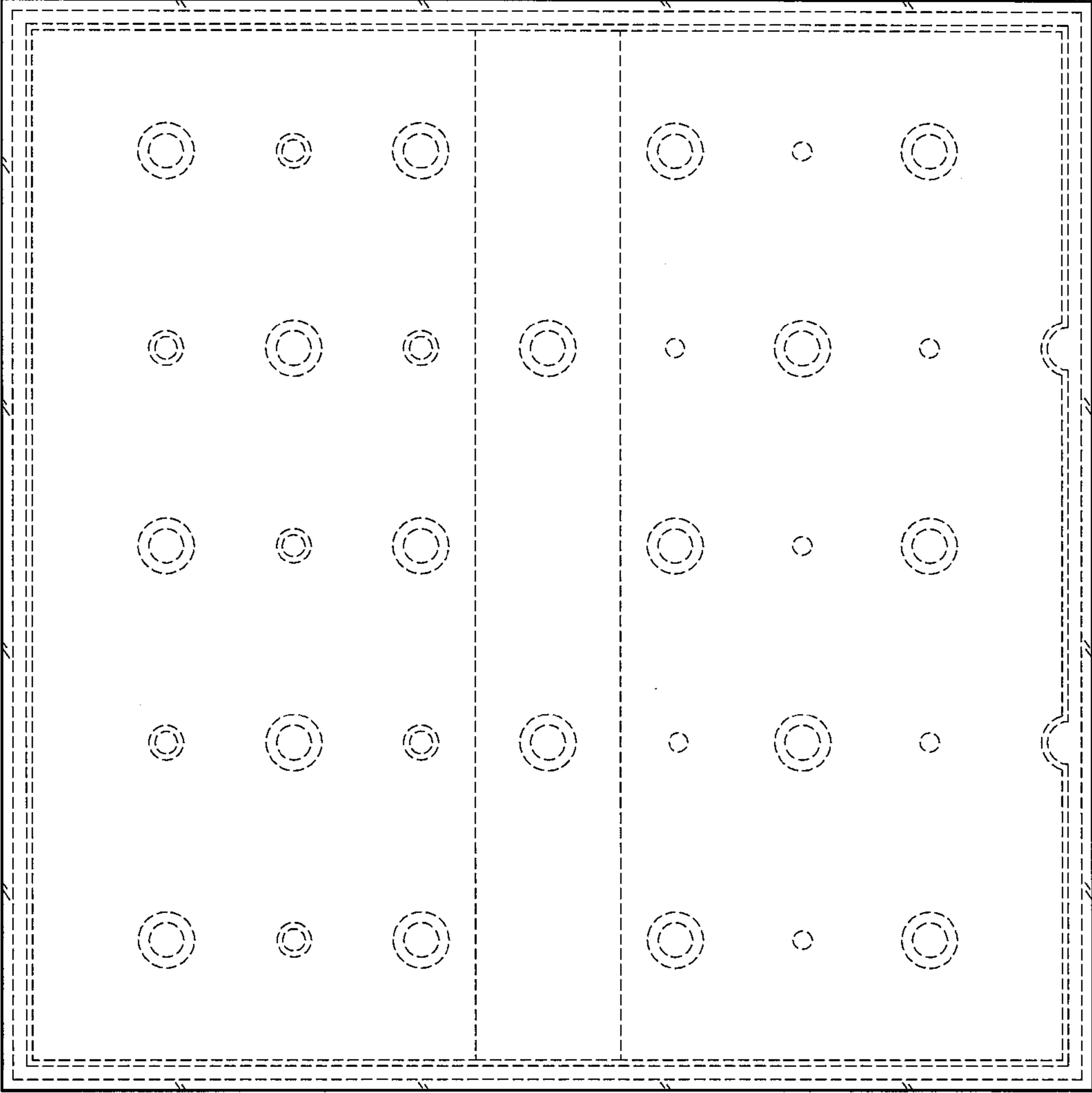


FIG. 2

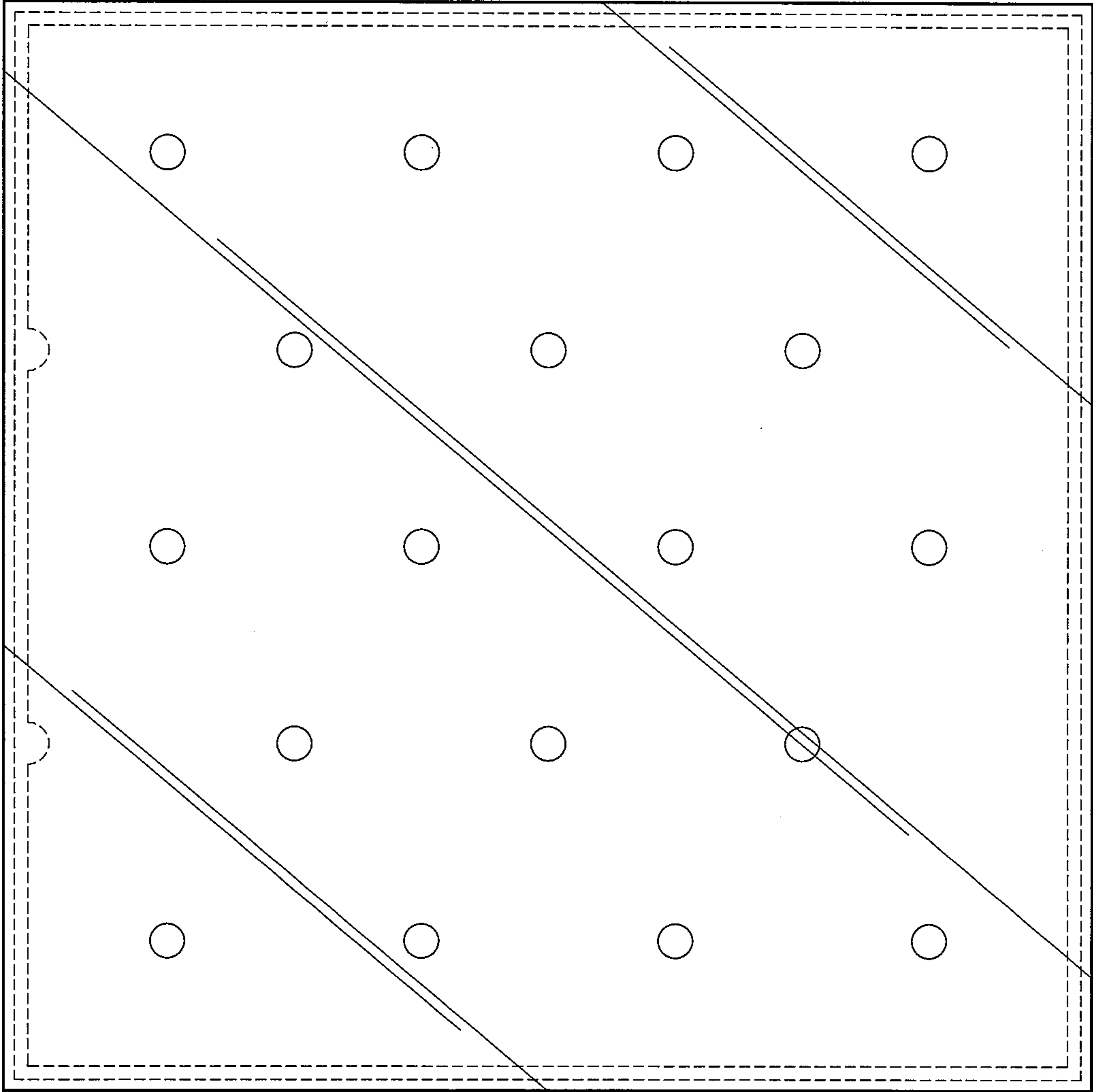


FIG. 3

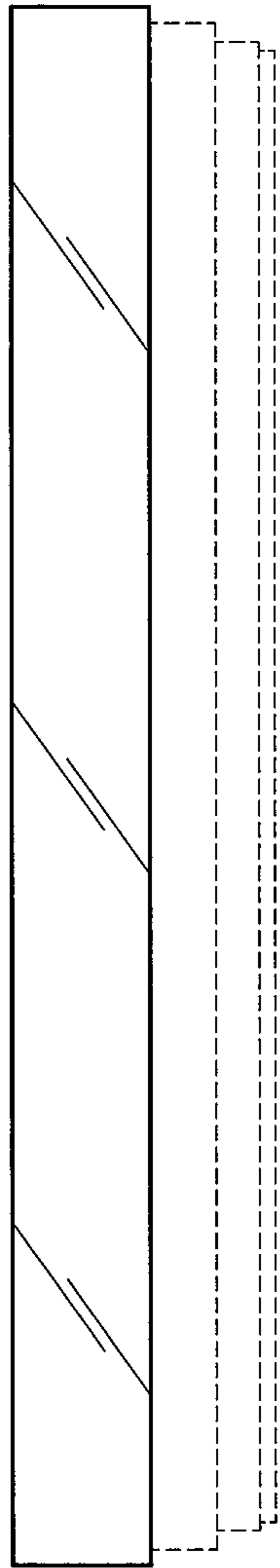


FIG. 4

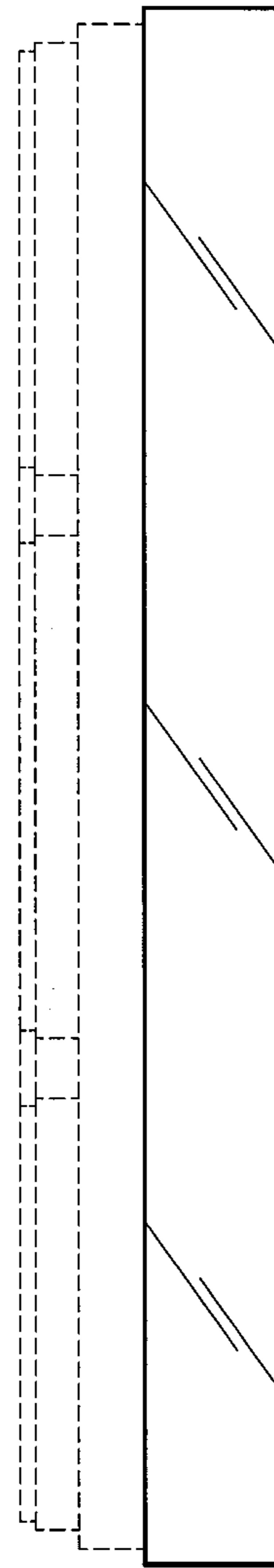


FIG. 5

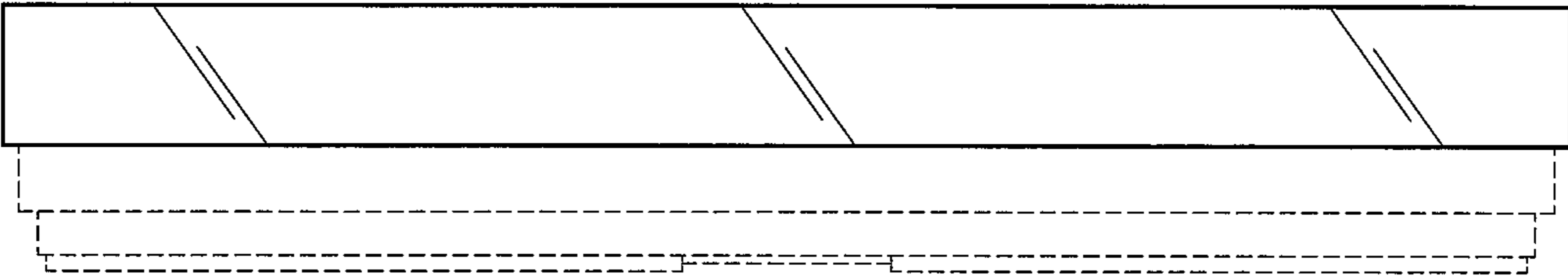


FIG. 6

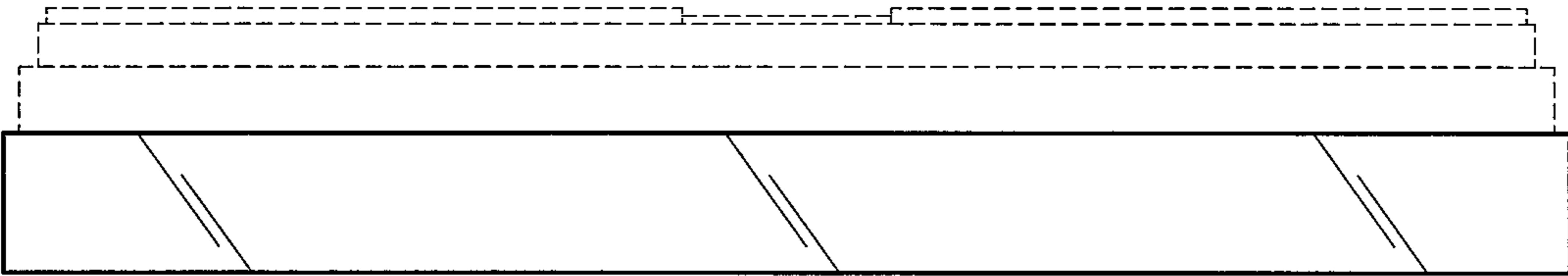


FIG. 7